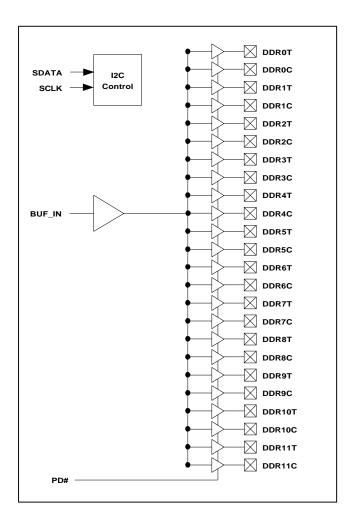


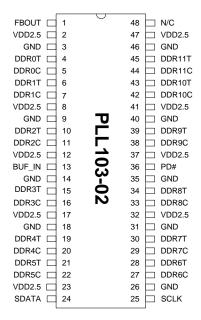
FEATURES

- Generates 24 output buffer from one input.
- Supports up to four DDR DIMMS.
- Supports 266MHz DDR SDRAM.
- One additional output for feedback.
- Less than 5ns delay.
- Skew between any outputs is less than 100 ps.
- 2.5V Supply range.
- Enhanced DDR Output Drive selected by I2C.
- Available in 48 pin SSOP.

BLOCK DIAGRAM



PIN CONFIGURATION



Note: #: Active Low

DESCRIPTIONS

The PLL103-02 Rev.D is designed as a 2.5V buffer to distribute high-speed clocks in PC applications. The device has 24 outputs. These outputs can be configured to support four unbuffered DDR DIMMS. The PLL103-02 Rev.D can be used in conjunction with the PLL202-04 or similar clock synthesizer for the VIA Pro 266 chipset.

The PLL103-02 Rev.D also has an I2C interface, which can enable or disable each output clock. When power up, all output clocks are enabled (has internal pull up).



PIN DESCRIPTIONS

Name	Number	Туре	Description
FBOUT	1	0	Feedback clock for chipset.
BUF_IN	13	I	Reference input from chipset.
PD	36	ı	Power Down Control input. When low, it will tri-state all outputs.
N/C	48		Not connected.
DDR[0:11]T	4,6,10,15,19, 21,28,30,34, 39,43,45	0	These outputs provide True copies of BUF_IN.
DDR[0:11]C	5,7,11,16,20, 22,27,29,33, 38,42,44	0	These outputs provide complementary copies of BUF_IN.
VDD2.5	2,8,12,17,23, 32,37,41,47	Р	2.5V power supply.
GND	3,9,14,18,26, 31,35,40,46	Р	Ground.



12C BUS CONFIGURATION SETTING

Address Assignment	A6	A5	A4	А3	A2	A1	Α0	R/W	
Address Assignment	1	1	0	1	0	0	1	_	
Slave Receiver/Transmitter	Provid	les both s	ave write	and readb	ack functi	onality			
Data Transfer Rate	Stand	ard mode	at 100kbi	:s/s					
Data Protocol	bytes must t termin	must be a be followe ate the tra	ccessed i d by 1 ack ansfer. Th	n sequenti knowledge e write or	al order fro bit. A byte read block	om lowest e transferre s both begi	to highest ed without ins with the	I from the con byte. Each by acknowledged master send	yte transferred d bit will
Data Protocol address and a write condition (0xD2) or a read condition (0xD3). Following the acknowledge of this address byte, in Write Mode: the Command Byte an Count Byte must be sent by the master but ignored by the slave, in Read Mode: the I Count Byte will be read by the master then all other Data Byte. Byte Count Byte defa power-up is = (0x09).						de: the Byte			

12C CONTROL REGISTERS

1. BYTE 6: Outputs Register (1=Enable, 0=Disable)

Bit	Pin#	Default	Description
Bit 7	48	1	Reserved
Bit 6	-	0	Reserved
Bit 5	-	0	Enhanced DDR Drive. 1 = Enhanced 25%
Bit 4	-	0	Reserved
Bit 3	45, 44	1	DDR11T, DDR11C
Bit 2	43, 42	1	DDR10T, DDR10C
Bit 1	39, 38	1	DDR9T, DDR9C
Bit 0	34, 33	1	DDR8T, DDR8C



2. BYTE 7: Outputs Register (1=Enable, 0=Disable)

Bit	Pin#	Default	Description
Bit 7	30, 29	1	DDR7T, DDR7C
Bit 6	28, 27	1	DDR6T, DDR6C
Bit 5	21, 22	1	DDR5T, DDR5C
Bit 4	19, 20	1	DDR4T, DDR4C
Bit 3	15, 16	1	DDR3T, DDR3C
Bit 2	10, 11	1	DDR2T, DDR2C
Bit 1	6, 7	1	DDR1T, DDR1C
Bit 0	4, 5	1	DDR0T, DDR0C



ELECTRICAL SPECIFICATIONS

1. Absolute Maximum Ratings

PARAMETERS	SYMBOL	MIN.	MAX.	UNITS
Supply Voltage	V_{DD}	V _{SS} -0.5	7.0	V
Input Voltage, dc	Vı	Vss-0.5	V _{DD} +0.5	V
Output Voltage, dc	Vo	Vss-0.5	V _{DD} +0.5	V
Storage Temperature	T _S	-65	150	°C
Ambient Operating Temperature	TA	0	70	°C
ESD Voltage			2	KV

Exposure of the device under conditions beyond the limits specified by Maximum Ratings for extended periods may cause permanent damage to the device and affect product reliability. These conditions represent a stress rating only, and functional operations of the device at these or any other conditions above the operational limits noted in this specification is not implied.

2. Operating Conditions

PARAMETERS	SYMBOL	MIN.	MAX.	UNITS
Supply Voltage	V _{DD2.5}	2.375	2.625	V
Input Capacitance	Cin		5	pF
Output Capacitance	Соит		6	pF

3. Electrical Specifications

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Input High Voltage	V _{IH}	All Inputs except I2C	2.0		V _{DD} +0.3	V
Input Low Voltage	VIL	All inputs except I2C	V _{SS} -0.3		0.8	V
Input High Current	liH	V _{IN} = V _{DD}			TBM	uA
Input Low Current	lıL	V _{IN} = 0			TBM	uA
Output High Voltage	V _{OH}	IOL = -12mA, VDD = 2.375V	1.7			V
Output Low Voltage	VoL	IOL = 12mA, VDD = 2.375V			0.6	V
Output High Current	Іон	VDD = 2.375V, VOUT=1V	-18	-32		mA
Output Low Current	loL	VDD = 2.375V, VOUT=1.2V	26	35		mA

Note: TBM: To be measured



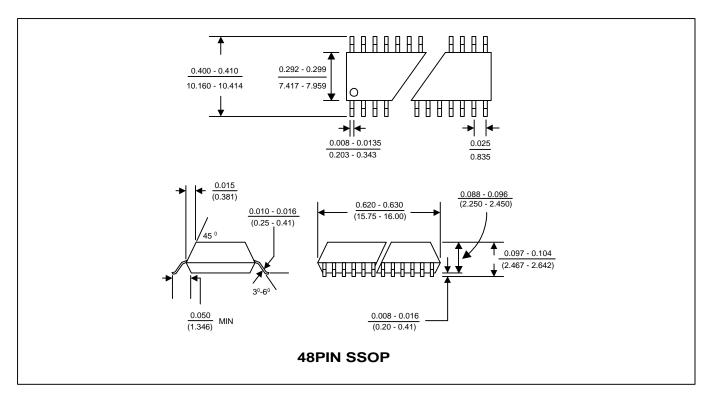
3. Electrical Specifications (Continued)

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Supply Current	I _{DDS}	PD = 0			TBM	mA
Output Crossing Voltage	Voc		(VDD/2) -0.1	VDD/2	(VDD/2)+ 0.1	V
Output Voltage Swing	V _{оит}		1.1		VDD-0.4	V
Duty Cycle	Dτ	Measured @ 1.5V	45	50	55	%
Max. Operating Frequency			66		170	MHz
Rising Edge Rate	Tor	Measured @ 0.4V ~ 2.4V	1.0	1.5	2.0	V/ns
Falling Edge Rate	T _{OF}	Measured @ 2.4V ~ 0.4V	1.0	1.5	2.0	V/ns
Clock Skew (pin to pin)	Tskew	All outputs equally loaded			100	ps
Stabilization Time	Тѕт				0.1	ms

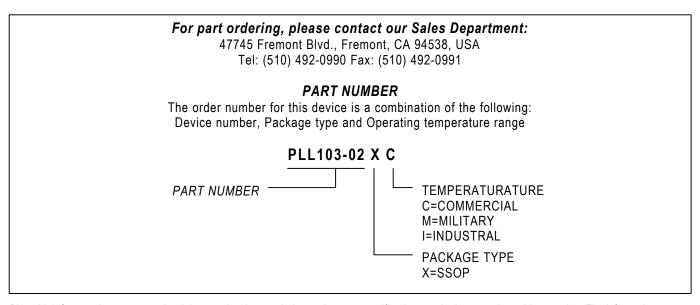
Note: TBM: To be measured



PACKAGE INFORMATION



ORDERING INFORMATION



PhaseLink Corporation, reserves the right to make changes in its products or specifications, or both at any time without notice. The information furnished by PhaseLink is believed to be accurate and reliable. However, PhaseLink makes no guarantee or warranty concerning the accuracy of said information and shall not be responsible for any loss or damage of whatever nature resulting from the use of, or reliance upon this product.

LIFE SUPPORT POLICY: PhaseLink's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of PhaseLink Corporation.